

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-16. (canceled)

17. (original) A wirebonder adapted to wire bond an integrated circuit chip to a substrate, the substrate having formed thereon a plurality of conductive traces, at least one of the conductive traces having a bond region containing a bond surface, the machine comprising:

a support structure positioning device;

a conditioning device positioned adjacent the support structure positioning device, the conditioning device and the support structure being movable relative to one another in a direction normal to the support structure, the conditioning device comprising:

a member;

a raised boss on the member, the raised boss being configured to compress bond surfaces on a top surface of the support structure when the conditioning device is engaged with the support structure;

a cavity located so as to receive therein an integrated circuit chip mounted on said support structure when the flexible member is engaged with the support structure; and

a bond wire capillary positioned over the circuit board clamp.

18. (original) The machine of claim 17 further comprising a heater connected to the conditioning device.

19. (original) The machine of claim 17 further comprising a vibrator connected to the conditioning device.

20. (original) The machine of claim 17 further comprising a servo motor attached to the conditioning device, the servo motor moving the conditioning device relative the support structure positioning device.